

REMARKS

The Examiner's Action mailed on October 5, 2011, has been received and its contents carefully considered.

In this Amendment, Applicants have amended claims 16 and 32, newly added claim 103, and cancelled claims 24 and 38-102 without prejudice. Claims 16 and 103 are the independent claims, and claims 16-23, 25-37 and 103 are pending in the application. For at least the following reasons, it is submitted that this application is in condition for allowance.

Applicant notes with appreciation the indication of allowable subject matter in claim 24 by the Examiner, although claim 24 was objected to as dependent from a rejected base claim. It is respectfully submitted that this objection should be withdrawn.

Independent claim 16 has been amended accordingly to recite "wherein a lateral distance between an outer periphery of the semiconductor chip and an edge of the opening of the insulating film is 0.1 mm or more", as originally recited in cancelled claim 24, and is therefore allowable, together with claims 17-23 and 25-37 that depend therefrom.

The drawings were objected to for not showing every feature recited in the claims, and claim 32 was objected to as not described in the specification. It is respectfully submitted that these objections should be withdrawn.

Claim 32 has been amended to recite "a functional element is not formed on an entirety of the functional surface of the semiconductor chip", which is supported by the drawings as originally filed.

As shown in FIG. 1, the functional element 4 is not formed in an end portion or periphery of the functional surface 3a of the semiconductor chip 3, so functional element 4 is not formed on an entirety of the functional surface of the semiconductor chip.

¶[0028] of the specification has been amended accordingly to further describe FIG. 1 as originally filed.

Claims 16-23, 25, 31 and 37 were rejected under 35 USC §102(b) as anticipated by *Seko* '704 (US 2002/0043704 A1), claims 26-28 were rejected under 35 USC §103(a) as obvious over *Seko* '704 in view of *Kojima et al.* (US 5,723,900), claims 29 and 30 were rejected under 35 USC §103(a) as obvious over *Seko* '704 in view of *Hashimoto* (US 6,515,370 B2), and claims 33-36 were rejected under 35 USC §103(a) as obvious over *Seko* '704 in view of *Seko* '240 (US 2004/0061240 A1). These rejections are each respectfully moot in light of the present Amendment.

New independent claim 103 is similar to the previous version of claim 16, but additionally recites "wherein the sealing layer does not cover an upper surface of the insulating film and the sealing layer covers a side face of the semiconductor chip up to a middle portion of the side face with respect to a thickness direction of the semiconductor chip".

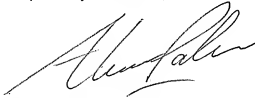
As the above features are not taught by any of the art of record, claim 103 is also allowable

It is submitted that this application is in condition for allowance. Such action and the passing of this case to issue are requested.

Should the Examiner feel that a conference would help to expedite the prosecution of this application, the Examiner is hereby invited to contact the undersigned counsel to arrange for such an interview.

No remittance is believed to be due. Should any fee be required, however, the Commissioner is hereby authorized to charge the fee to our Deposit Account No. 18-0002, and advise us accordingly.

Respectfully submitted,



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Date

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